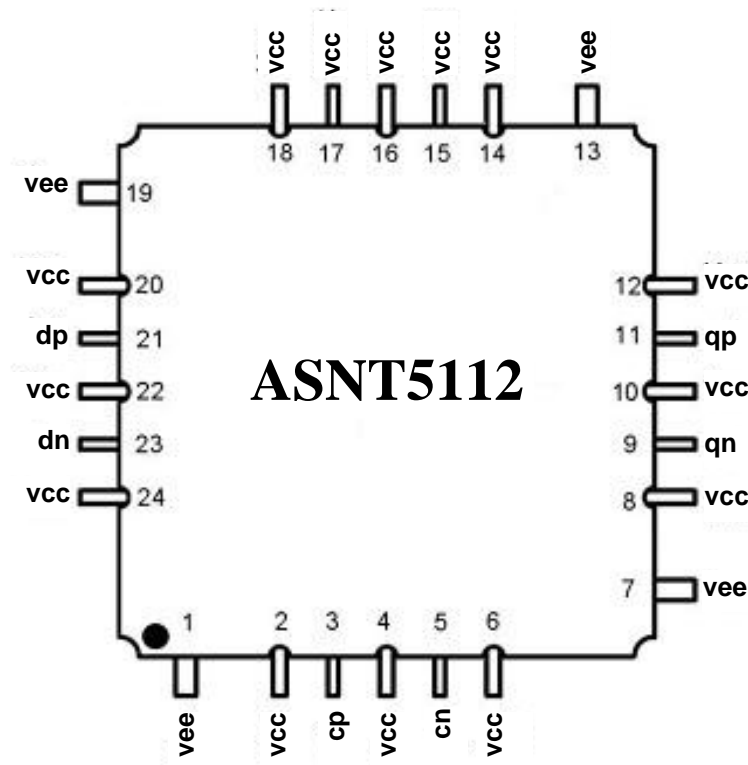# ASNT5112-KMC
DC-32*Gbps* High Sensitivity D-Type Flip-Flop

- High speed broadband D-Type Flip-Flop for data retiming with full rate clock

- Sensitive input data buffer with increased common-mode voltage range to support sampling applications

- Exhibits low jitter and limited temperature variation over industrial temperature range

- 4*ps* set-up/hold time capability

- 88% clock phase margin for retiming of data input eye

- Fully differential CML input interfaces

- Fully differential CML output interface with 400*mV* single-ended swing

- Single +3.3*V* or -3.3*V* power supply

- Power consumption: 345*mW*

- Fabricated in SiGe for high performance, yield, and reliability
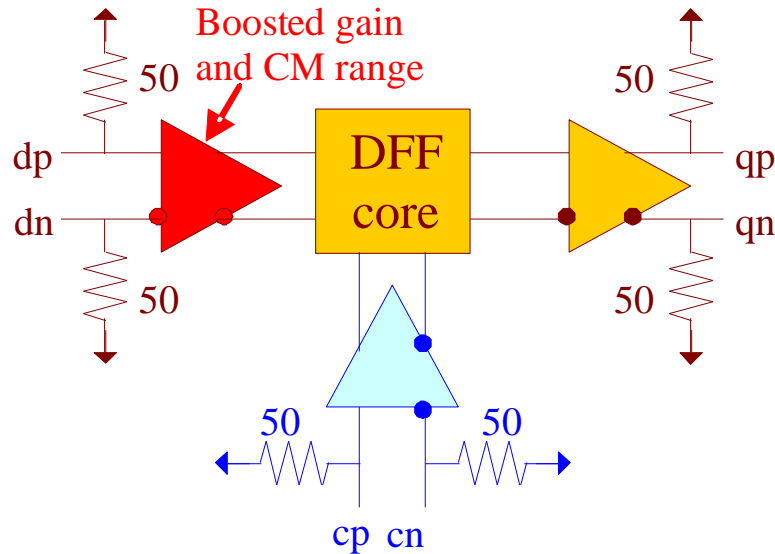
- Custom CQFP 24-pin package

DESCRIPTION

Fig. 1. Functional Block Diagram

The temperature stable ASNT5112-KMC SiGe IC provides broadband data retiming functionality, and is intended for use in high-speed measurement / test equipment. The IC shown in Fig. 1 can sample a high-speed data signal dp/dn with a full-rate external clock cp/cn to create a full-rate retimed NRZ data output qp/qn.

The data input buffer is designed to have increased input signal sensitivity, and is able to operate over a wider range of input common mode (CM) voltages. The part's I/O's support the CML logic interface with on chip $50 Ohm$ termination to vcc, and may be used differentially, AC/DC coupled, single-ended, or in any combination (see also POWER SUPPLY CONFIGURATION). In the DC-coupling mode, the input signal's common mode voltage should comply with the specifications shown in ELECTRICAL CHARACTERISTICS. In the AC-coupling mode, the input termination provides the required common mode voltage automatically. The differential DC signaling mode is recommended for optimal performance.

POWER SUPPLY CONFIGURATION

The part can operate with either a negative supply (vcc = $0.0V$ = ground and vee = $-3.3V$), or a positive supply (vcc = $+3.3V$ and vee = $0.0V$ = ground). In case of a positive supply, all I/Os need AC termination when connected to any devices with $50 Ohm$ termination to ground. Different PCB layouts will be needed for each different power supply combination.

All the characteristics detailed below assume vcc = 0.0*V* and vee = -3.3*V*.

ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings shown in Table 1 may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground (assumed vcc).

Table 1. Absolute Maximum Ratings

Parameter	Min	Max	Units
Supply Voltage (vee)		-3.6	*V*
Power Consumption		0.38	*W*
RF Input Voltage Swing (SE)		1.0	*V*
Case Temperature		+90	*ºC*
Storage Temperature	-40	+100	*ºC*
Operational Humidity	10	98	*%*
Storage Humidity	10	98	*%*

TERMINAL FUNCTIONS

TERMINAL			DESCRIPTION
Name	**No.**	**Type**	
High-Speed I/Os			
dp	21	CML input	Differential high-speed data inputs with internal SE 50*Ohm* termination to vcc
dn	23		
cp	3	CML input	Differential high-speed clock inputs with internal SE 50*Ohm* termination to vcc
cn	5		
qp	11	CML output	Differential high-speed full-rate data outputs. Require external SE 50*Ohm* termination to vcc
qn	9		
Supply and Termination Voltages			
Name	**Description**		**Pin Number**
vcc	Positive power supply (+3.3*V* or 0*V*)		2, 4, 6, 8, 10, 12, 14, 15, 16, 17, 18, 20, 22, 24
vee	Negative power supply (0*V* or -3.3*V*)		1, 7, 13, 19

ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
General Parameters					
vee	-3.1	-3.3	-3.5	*V*	±6%
vcc		0.0		*V*	External ground
*I*vee		105		*mA*	
Power consumption		345		*mW*	
Junction temperature	-40	25	125	*°C*	
Input Data (dp/dn)					
Data Rate	DC		32	*Gbps*	
Swing	0.05		0.8	*V*	Differential or SE, p-p
CM voltage level	vcc-1.2	vcc -0.3	vcc	*V*	Must match for both inputs
Input Clock (cp/cn)					
Frequency	DC		32	*GHz*	
Swing	0.05		0.8	*V*	Differential or SE, p-p
CM Voltage Level	vcc-0.8		vcc	*V*	Must match for both inputs
Duty cycle	40	50	60	*%*	
Clock phase margin	86	88	90	*%*	For reliable data latching
HS Output Data (qp/qn)					
Data Rate	DC		32	*Gbps*	
Logic "1" level		vcc		*V*	
Logic "0" level		vcc-0.4		*V*	With external 50*Ohm* DC termination
Rise/Fall times			13	*ps*	20%-80%
Output Jitter			2.5	*ps*	Peak-to-peak

PACKAGE INFORMATION

The chip die is housed in a custom 24-pin CQFP package shown in Fig. 2. The package provides a center heat slug located on its back side to be used for heat dissipation. ADSANTEC recommends for this section to be soldered to the vcc plain, which is ground for a negative supply, or power for a positive supply.

The part's identification label is ASNT5112-KMC. The first 8 characters of the name before the underscore identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the underscore represent the package's manufacturer, type, and pin out count.

This device complies with the Restriction of Hazardous Substances (RoHS) per 2011/65/EU for all ten substances.
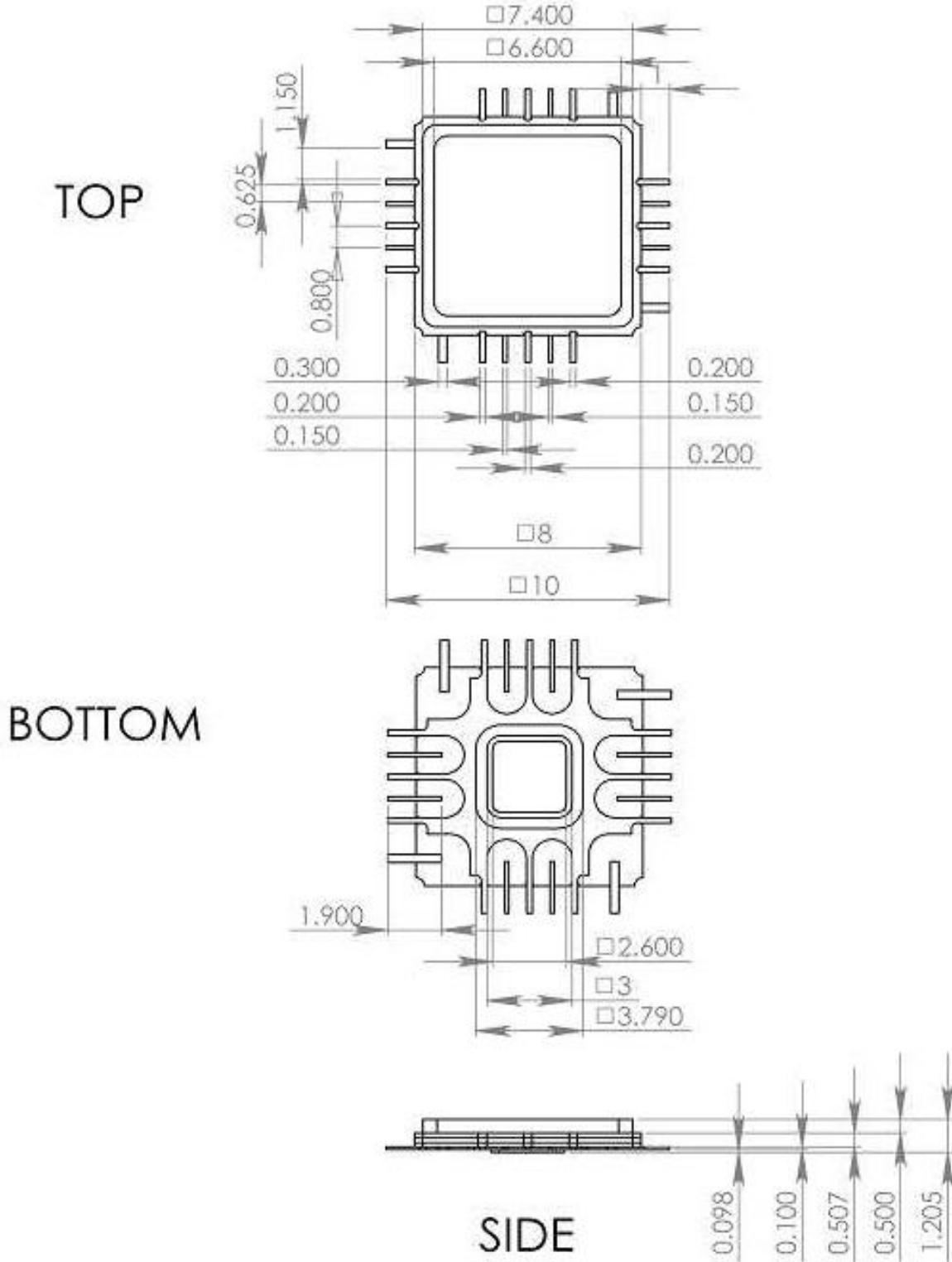
Fig. 2. CQFP 24-Pin Package Drawing (All Dimensions in mm)

REVISION HISTORY

Revision	Date	Changes
3.7.2	02-2020	Updated Package Information
3.6.2	07-2019	Updated Letterhead
3.6.1	03-2017	Updated Description section
		Updated Power Supply Configuration section
		Updated Terminal functions section
		Revised Electrical Characteristics section
		Revised Package Information section
3.5.1	02-2013	Revised terminal functions
		Revised electrical characteristics section
3.4.1	02-2013	Revised title
		Revised package pin out drawing
		Revised functional block diagram
		Revised description
		Revised terminal functions
		Revised electrical characteristics section
		Revised package information section
3.3.1	01-2013	Corrected pin out drawing
		Revised electrical characteristics section
		Corrected phase margin specification
3.2.1	01-2013	Corrected format
		Added package drawing
		Corrected absolute maximum ratings table
3.1	02-2012	Revised power supply configuration section
		Revised package information section
3.0	01-2012	Added power supply configuration text
		Added absolute maximum ratings table
		Revised electrical characteristics section
		Revised package information section
2.0	02-2009	Revised electrical characteristics section
		Revised package information section
1.0	01-2009	First release